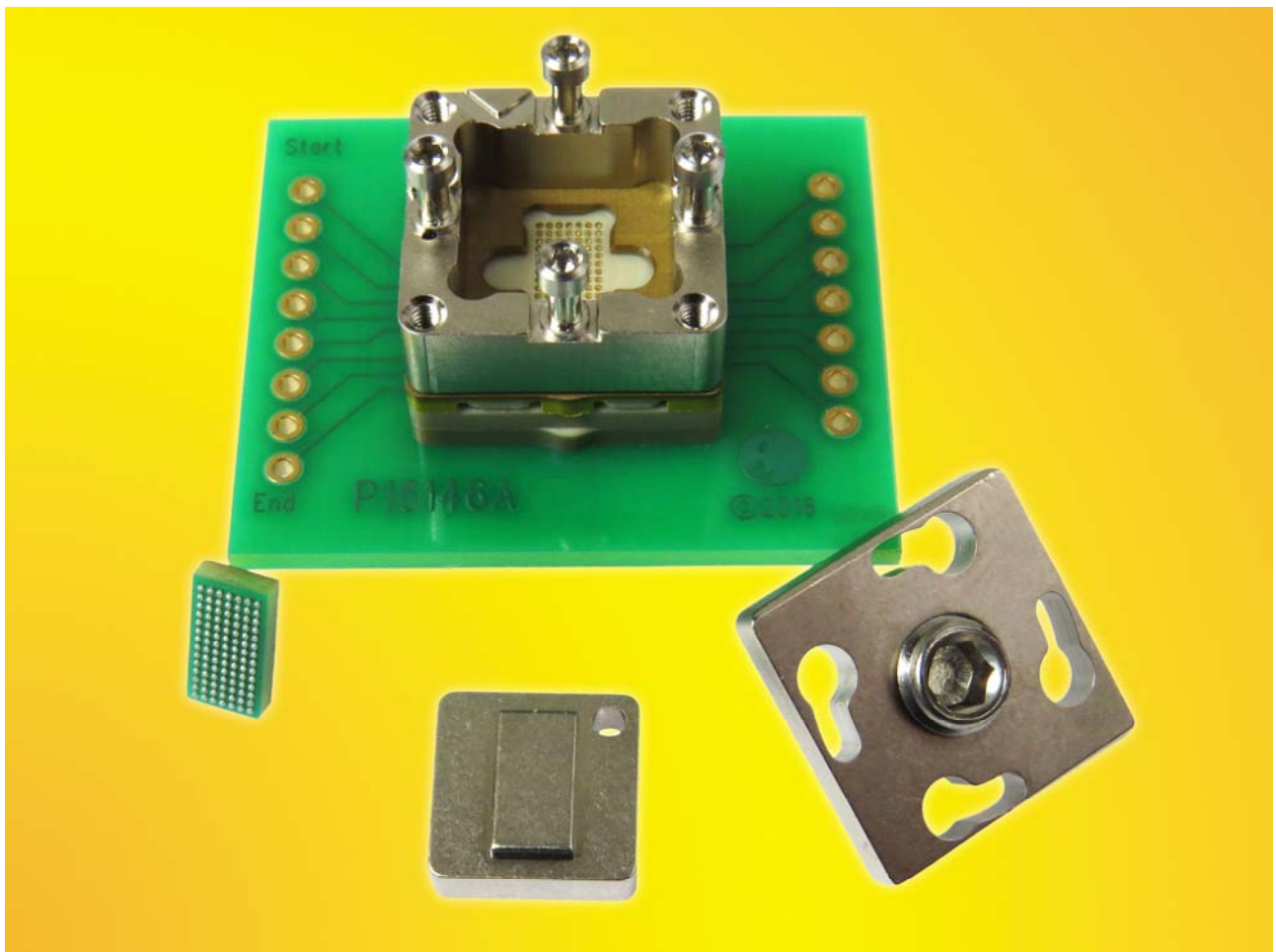




Swivel Lid Spring Pin BGA Socket for IDT's wireless power receiver

Socket your 98 pin BGA using Extreme Temperature Socket with Superior Electrical Performance

EAGAN, MN - August, 2016 - Ironwood Electronics recently introduced a new BGA socket addressing high performance requirements for testing BGA devices - SBT-BGA-7033. The contactor is a stamped spring pin with 31 gram actuation force per ball and cycle life of 125,000 insertions. The self inductance of the contactor is 0.88 nH, insertion loss < 1 dB at 15.7 GHz and capacitance 0.097pF. The current capacity of each contactor is 4 amps at 30 °C temperature rise. Socket temperature range is -55 °C to +180 °C. Socket also features a floating guide for precise ball to pin alignment. The specific configuration of the package to be tested in the SBT-BGA-7033 is IDT's wireless power receiver chip (BGA, 4x7.5mm, 0.5mm pitch, 98 position, 7x14 ball array) used to wirelessly charge Galaxy S7. The socket is mounted using supplied hardware on the target PCB with no soldering. To use, place the BGA device into the socket base and swivel socket lid on to the base using the shoulder screws. The socket uses a compression screw to apply downward pressure enabling the device be interconnected to the target PCB. This socket can be used for hand test and characterization applications with the most stringent requirements.



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